12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20141007001A
Die Conversion for Select AUP LL Devices in DBV, DCK and DRL Package
Final Change Notification / Sample Request

Dear Customer:

Revision A is to announce the retraction of select devices.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

PCN# 20141007001A
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20141007001A	**PCN Date:**	2/19/2015
Title:	Die Conversion for select AUP LL Devices in DBV, DCK and DRL Packages		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	01/09/2015	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☒	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Revision A is to announce the retraction of select devices. Retracted devices are identified with a ~~**strikethrough**~~ and are highlighted in yellow in the Product Affected Section. These devices will remain on the current Die Revision.

This change notification is to announce a Die Conversion for select AUP LL Devices. The Die Revision will change from X/A to C. Devices affected by this change are listed in the product affected section of this notification. There will be no change to the data sheet.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Reliability & electrical characterization evaluation showed no adverse impacts.

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in table & sample label below:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
X/A	**C**

Sample product shipping label to indicate die rev location (**not actual product label**)

Die Rev Marking:
Current = X/A
New = C

Product Affected:			
SN74AUP1G00DBVR	SN74AUP1G08DBVR	SN74AUP1G240DBVR	~~SN74AUP1G58DCKT~~
SN74AUP1G00DBVT	SN74AUP1G08DBVT	SN74AUP1G240DBVT	~~SN74AUP1G58DRLR~~
SN74AUP1G00DCKT	SN74AUP1G08DCKT	SN74AUP1G240DCKT	SN74AUP1G79DBVR
~~SN74AUP1G00DRLR~~	~~SN74AUP1G08DRLR~~	SN74AUP1G32DBVR	SN74AUP1G79DBVT
SN74AUP1G02DBVR	SN74AUP1G125DBVR	SN74AUP1G32DBVT	SN74AUP1G79DCKT
SN74AUP1G02DBVT	SN74AUP1G125DBVT	SN74AUP1G32DCKT	~~SN74AUP1G79DRLR~~
SN74AUP1G02DCKT	SN74AUP1G125DCKT	~~SN74AUP1G32DRLR~~	SN74AUP1G80DBVR
~~SN74AUP1G02DRLR~~	~~SN74AUP1G125DRLR~~	SN74AUP1G34DBVR	SN74AUP1G80DBVT
SN74AUP1G04DBVR	SN74AUP1G126DBVR	SN74AUP1G34DBVT	SN74AUP1G80DCKT
SN74AUP1G04DBVT	SN74AUP1G126DBVT	SN74AUP1G34DCKT	~~SN74AUP1G97DBVR~~
SN74AUP1G04DCKT	SN74AUP1G126DCKT	~~SN74AUP1G34DRLR~~	~~SN74AUP1G97DBVT~~
~~SN74AUP1G04DRLR~~	~~SN74AUP1G126DRLR~~	~~SN74AUP1G57DBVR~~	~~SN74AUP1G97DCKR~~
SN74AUP1G06DBVR	SN74AUP1G14DBVR	~~SN74AUP1G57DBVT~~	~~SN74AUP1G97DCKT~~
SN74AUP1G06DBVT	SN74AUP1G14DBVT	~~SN74AUP1G57DCKR~~	~~SN74AUP1G97DRLR~~
SN74AUP1G06DCKT	SN74AUP1G14DCKT	~~SN74AUP1G57DCKT~~	~~SN74AUP1G98DBVR~~
~~SN74AUP1G06DRLR~~	~~SN74AUP1G14DRLR~~	~~SN74AUP1G57DRLR~~	~~SN74AUP1G98DBVT~~
SN74AUP1G07DBVR	SN74AUP1G17DBVR	~~SN74AUP1G57DRLR-P~~	~~SN74AUP1G98DCKR~~
SN74AUP1G07DBVT	SN74AUP1G17DBVT	~~SN74AUP1G58DBVR~~	~~SN74AUP1G98DCKT~~
SN74AUP1G07DCKT	SN74AUP1G17DCKT	~~SN74AUP1G58DBVT~~	~~SN74AUP1G98DRLR~~
~~SN74AUP1G07DRLR~~	~~SN74AUP1G17DRLR~~	~~SN74AUP1G58DCKR~~	

Reference Qualification Data: (Approved 11/29/2010)

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device Construction Details:

Qualification Vehicle #1: **SN74AUP1G00DCKR**

Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #2: **SN74AUP1G02DCKR**

Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #3: **SN74AUP1G04DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #4: **SN74AUP1G06DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #5: **SN74AUP1G07DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #6: **SN74AUP1G08DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #7: **SN74AUP1G125DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #8: **SN74AUP1G126DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
X-Ray	Bottom Side only	5/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #9: **SN74AUP1G14DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #10: **SN74AUP1G17DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #11: **SN74AUP1G240DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #12: **SN74AUP1G32DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #13: **SN74AUP1G34DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #14: **SN74AUP1G79DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

Qualification Vehicle #15: **SN74AUP1G80DCKR**			
Wafer Fab Site:	FREISING	Wafer Process:	P9722
Protective Die Coating:	10KACN		

Qualification: ☐ **Plan** ☒ **Test Results**		
Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
ESD (CDM)	1500 V	3/0
Manufacturability	Wafer Fab (per mfg. Site specification)	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
Notes: Qualification tests “pass” on zero fails for each test		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com